

Data requirements for semiconductor die —

Part 5-3: Particular requirements and recommendations for die types — Minimally-packaged die

ICS 31.080

National foreword

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Summary of pages

This document comprises a front cover, an inside front cover, the ES title page, pages 2 to 8, an inside back cover and a back cover.

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English version

Data requirements for semiconductor die
Part 5-3: Particular requirements and recommendations for die types -
Minimally-packaged die

This European Specification was approved by CENELEC on 2001-08-21.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

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Foreword

This European Specification has been prepared by the CENELEC BTTF 97-1, Known Good Die.

It was submitted to the National Committees for comments and was agreed at the CENELEC BTTF 97-1 meeting on 2001-08-21.

The following date was fixed:

- latest date by which the existence of the ES
has to be announced at national level (doa) 2002-02-01

The structure of this European Specification is as follows:

ES 59008 Data requirements for semiconductor die

- Part 1 General requirements
- Part 2 Vocabulary
- Part 3 Mechanical, material and connectivity requirements
- Part 4 Specific requirements and recommendations
 - Part 4-1 Test and quality
 - Part 4-2 Handling and storage
 - Part 4-3 Thermal
 - Part 4-4 Electrical simulation
- Part 5 Particular requirements and recommendations for die types
 - Part 5-1 Bare die
 - Part 5-2 Bare die with added connection structures
 - Part 5-3 Minimally packaged die
- Part 6 Exchange data formats and data dictionary
 - Part 6-1 Data exchange - DDX
 - Part 6-2 Data dictionary